## DA2JF81

### Silicon epitaxial planar type

For high speed switching circuits

#### ■ Features

- ullet Small reverse current  $I_R$
- $\bullet$  High repetitive peak reverse voltage  $V_{\text{RRM}}$
- Contributes to miniaturization of sets, reduction of component count.
- Eco-friendly Halogen-free package

#### ■ Packaging

Embossed type (Thermo-compression sealing): 3000 pcs / reel (standard)

#### ■ Absolute Maximum Ratings $T_a = 25$ °C

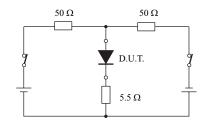
Parameter	Symbol	Rating	Unit	
Repetitive peak reverse voltage	V <sub>RRM</sub>	800	V	
Non-repetitive peak reverse surge voltage	V <sub>RSM</sub>	V <sub>RSM</sub> 800		
Forward current	$I_F$	200	mA	
Non-repetitive peak forward surge current *1, 2	I <sub>FSM</sub>	1	A	
Junction temperature	T <sub>j</sub>	-40 to +150	°C	
Storage temperature	T <sub>stg</sub>	-40 to +150	°C	

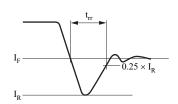
Note) \*1: Mounted on an alumina PC board

### ■ Electrical Characteristics T<sub>a</sub> = 25°C±3°C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	$V_{\mathrm{F}}$	$I_F = 200 \text{ mA}$			2.5	V
Reverse current	I <sub>RRM1</sub>	$V_{RRM} = 400 V$			1	μА
	I <sub>RRM2</sub>	$V_{RRM} = 800 V$			10	
Terminal capacitance	C <sub>t</sub>	$V_R = 0 V, f = 1 MHz$		0.6		pF
Reverse recovery time *	t <sub>rr</sub>	$I_F = 100 \text{ mA}, I_R = 200 \text{ mA},$ $I_{rr} = 0.25 \times I_R$		10	45	ns

- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
  - 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
  - 3. \*: t<sub>rr</sub> measurement circuit





#### ■ Package

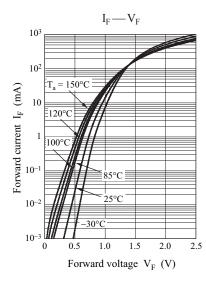
• Code

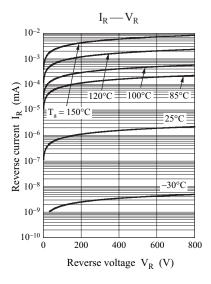
SMini2-F5-B

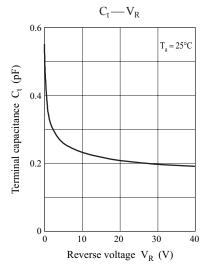
- Pin Name
  - 1: Cathode
  - 2: Anode
- Marking Symbol: 5A

<sup>\*2: 50</sup> Hz sine wave 1 cycle (Non-repetitive peak current)

DA2JF81 Panasonic



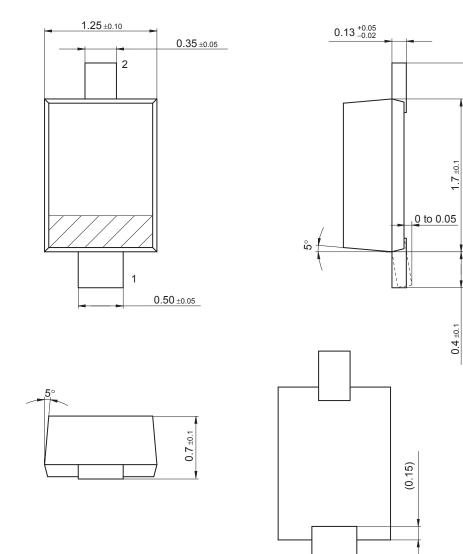




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### SMini2-F5-B

Unit: mm



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